

IN THE CLAIMS:

Please amend claim 20.

20. (currently amended) A printed circuit board assembly comprising:
- a printed circuit board[.,,];
 - an IC die electronically coupled to the printed circuit board;
 - a thermal interface material comprising an inorganic material in direct contact with the IC die; and
 - a thermally conductive heat spreader body coated with an organic surface protectant in direct contact with the thermal interface material.